

Refining & Chemicals Polymers Technical data sheet High Density Polyethylene Produced in Europe

Description

Circular compound rPE 5673 is a high density polyethylene, containing 70% of recycled HDPE originating from post-consumer waste collected in Western European countries.

Circular compound rPE 5673 is suited for the manufacture of multilayer films for various applications such as collation shrink, furniture covers, tissue wraps etc. It is also suited for the manufacture of blow moulded packaging for household and industrial liquids. The compound is odour free, natural in colour and exhibits very good stress-cracking resistance.

Circular compound rPE 5673 is not intended for food contact, pharmaceutical nor medical applications.

Characteristics

Property	Method	Unit	Typical value (*)
Density	ISO 1183	g/cm³	0.957
Melt Flow Rate (190°C/2.16 kg)	ISO 1133/D	g/10 min	0.30
Melt Flow Rate (190°C/21.6 kg)	ISO 1133/G	g/10 min	30
ESCR Antarox 100%	ASTM D 1693/B	h	F ₅₀ = 50

(*) Data not intended for specification purposes

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: <u>www.polymers.totalenergies.com</u>.

Information contained in this publication is true and accurate at the time of publication and to the best of our knowledge. The nominal values stated herein are obtained using laboratory test specimens. These are typical values not to be construed as specification limits. Before using one of the products mentioned herein, customers and other users should take all care in determining the suitability of such product for the intended use. Unless specifically indicated, the products mentioned herein are not suitable for applications in the pharmaceutical or medical sector. The Companies within TotalEnergies Petrochemicals do not accept any liability whatsoever arising from the use of this information or the use, application or processing of any product decribed herein. No information contained in this publication can be considered as a suggestion to infringe patents. The Companies disclaim any liability that may be claimed for infringement or alleged infringement of patents.